

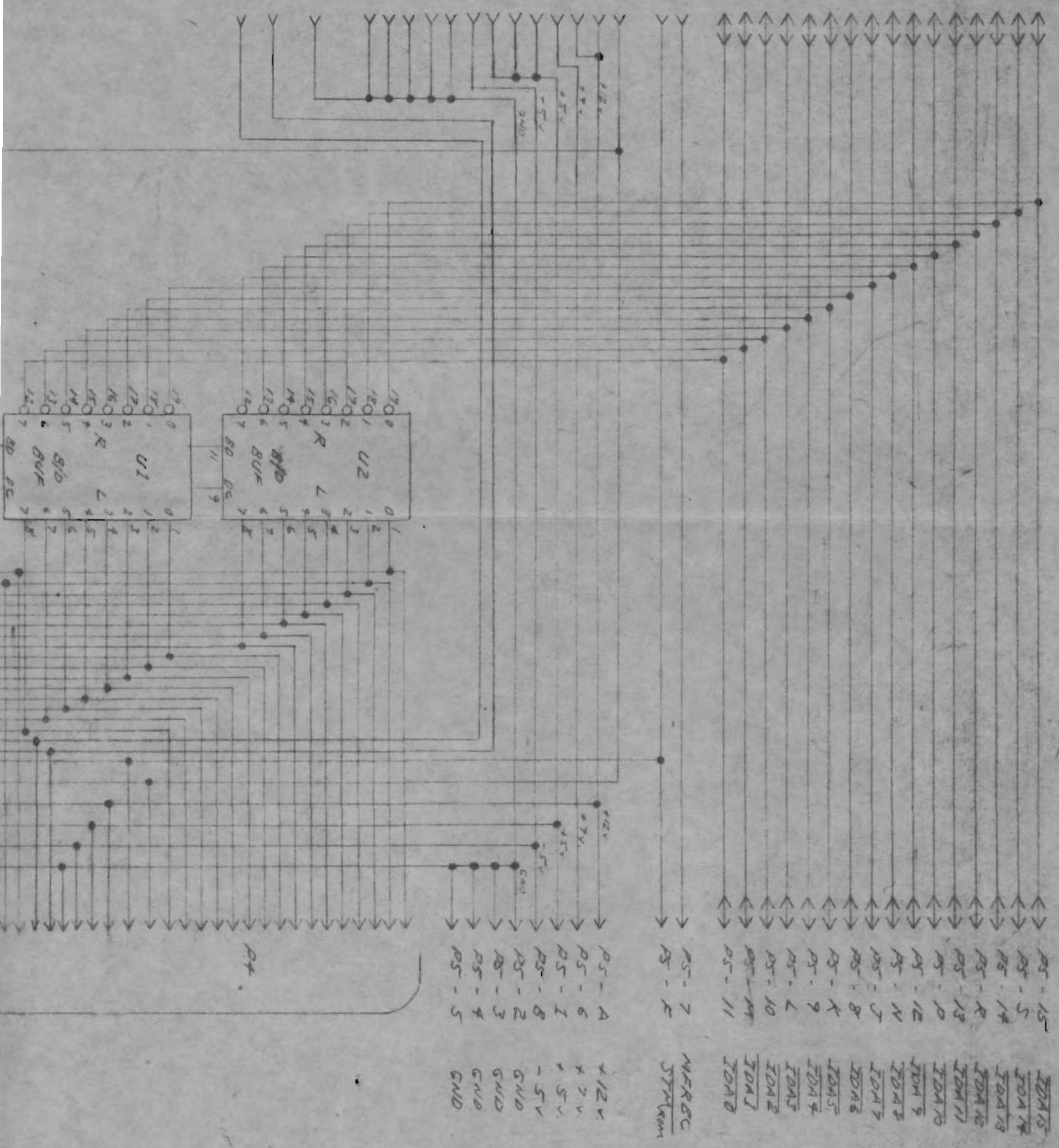
ENGINEERING RESPONSIBILITY										SEPIA					
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
16	17	18	19	20	21	22			33	34	38		42	43	
		63		90				93							

C-09825-66512-1

SYM	REVISIONS	APPROVED	DATE
	A AS ISSUED	AC	12-14-75
B	ADDED 14, 15, WRIT ₃ BYTE	09-13392	4-27-76

WRIT P.L. 34
BYTE P.L. 38

IR8C	PC-28	PC-16	IR8C	PC-28	PC-16
*12V	PC-17	PC-14	*12V	PC-17	PC-14
*7V	PC-19	PC-12	*7V	PC-19	PC-12
*5V	PC-40	PC-10	*5V	PC-40	PC-10
*5V	PC-25	PC-8	*5V	PC-25	PC-8
*5V	PC-27	PC-10	*5V	PC-27	PC-10
*5V	PC-29	PC-15	*5V	PC-29	PC-15
-5V	PC-20	PC-2	-5V	PC-20	PC-2
GND	PC-31	PC-6	GND	PC-31	PC-6
GND	PC-33	PC-4	GND	PC-33	PC-4
GND	PC-35	PC-8	GND	PC-35	PC-8
GND	PC-37	PC-10	GND	PC-37	PC-10
GND	PC-39	PC-15	GND	PC-39	PC-15
GND	PC-27	PC-12	GND	PC-27	PC-12
GND	PC-29	PC-10	GND	PC-29	PC-10
GND	PC-31	PC-8	GND	PC-31	PC-8
GND	PC-33	PC-6	GND	PC-33	PC-6
GND	PC-35	PC-4	GND	PC-35	PC-4
GND	PC-37	PC-2	GND	PC-37	PC-2
GND	PC-39	PC-1	GND	PC-39	PC-1



ITEM	QTY	MATERIAL DESCRIPTION	MAT'L-PART NO.	MAT'L-DWG. NO.	MAT'L-SPEC.
------	-----	----------------------	----------------	----------------	-------------

DO NOT SCALE THIS DRAWING
UNLESS OTHERWISE SPECIFIED.
DIMENSIONS ARE IN INCHES.
TOLERANCES .XX ± .02 .XXX ± .005

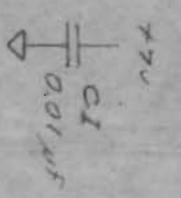
DRAWN BY: *John Nelson* DATE: 9/20/74
ENGINEER: *John Nelson* DATE: 9/20/74
RELEASE TO PROD: *L. Chandler* DATE: 10-14-75

TITLE: ROM INTERFACE
NEXT ASSEMBLY:

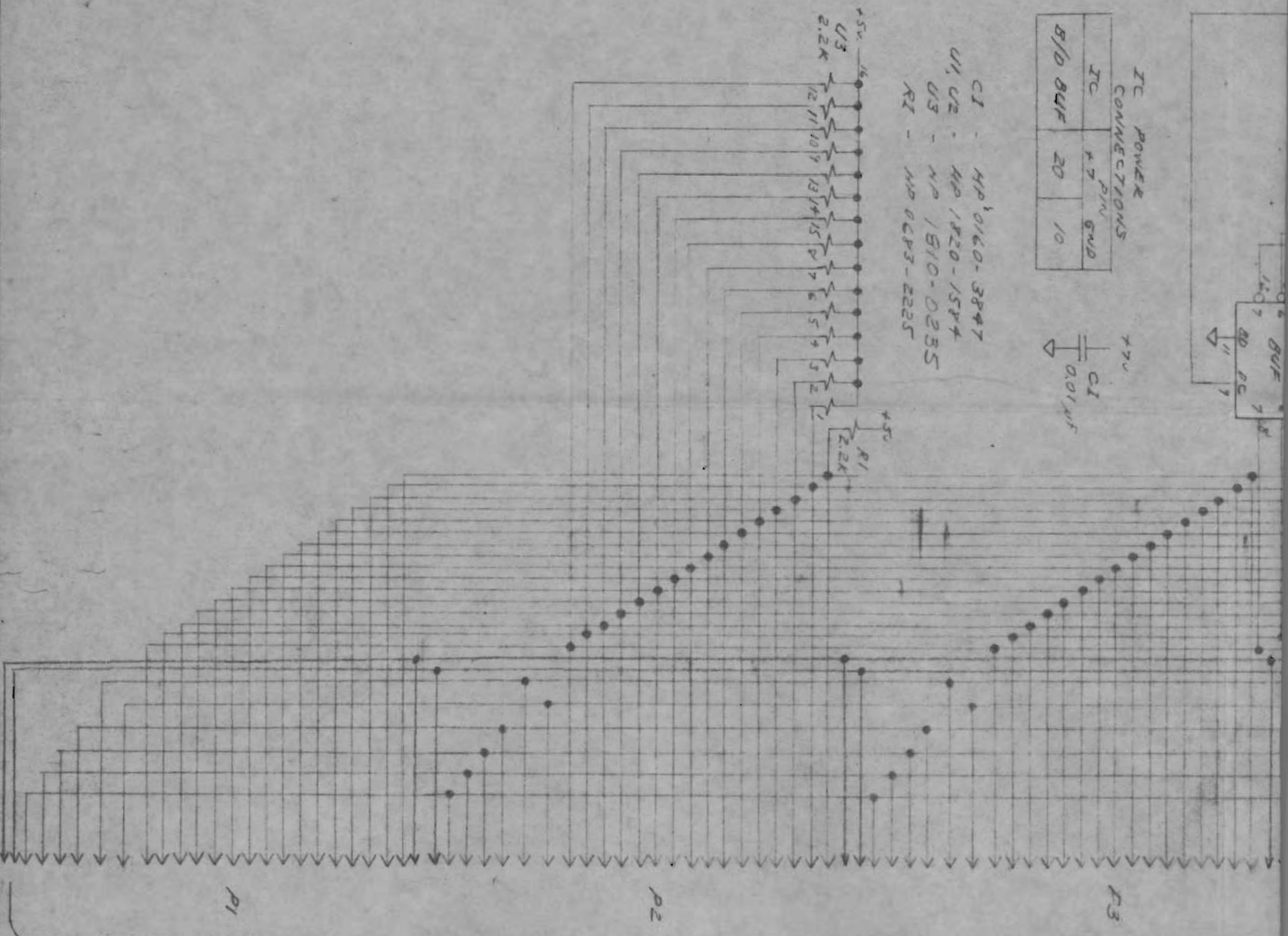
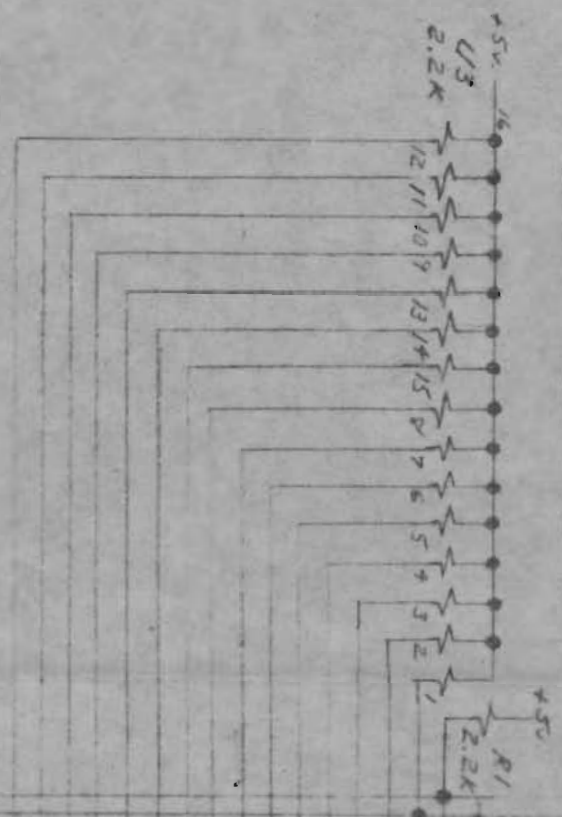
HEWLETT PACKARD
PART NUMBER: 09825-66512
C-09825-66512-1

IC POWER CONNECTIONS

IC	+7	PIN	GND
B/D BUF	20		10



- C1 - HP 0160-3847
- U1, U2 - HP 1820-1584
- U3 - HP 1810-0235
- R1 - HP 0CP3-2225



P1 thru P4 CONNECTIONS

PIN	SIGNAL
3	IDPA15
D	IDPA14
4	IDPA13
E	IDPA12
5	IDPA11
F	IDPA10
6	IDPA9
H	IDPA8
7	IDPA7
J	IDPA6
S	IDPA5
K	IDPA4
9	IDPA3
L	IDPA2
10	IDPA1
M	IDPA0
C	PIRBC
11	STMA _{room}
13	+12V
N	+5V
P	-5V
12	GND
15	WRITE
14	BYTE